

HITANO ENTERPRISE CORP.

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SPECIFICATION FOR CAPACITOR ARRAY

Series. : <u>CA Series</u>

Description: Size 0508 & 0612, COG(NPO), X7R, Y5V

<u>16Vdc ~ 50Vdc</u>

<u>DRAWN BY</u>	CHECKED BY	APPROVED BY
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1. INTRODUCTION

HITANO middle and high voltage series MLCC is designed by a special internal electrode pattern, which can reduce voltage concentrations by distributing voltage gradients throughout the entire capacitor. This special design also affords increased capacitance values in a given case size and voltage rating.

HITANO capacitor arrays are developed to offer designers the opportunity to lower placement costs increase assembly line output through lower component count per board.

2. FEATURES

- High density mounting due to mounting space saving.
- Mounting cost saving.
- Increased throughput.
- RoHS compliant. & HALOGEM compliant

3. APPLICATIONS

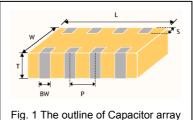
- » For use as a bypass for digital and analog signal line noise
- » Computer motherboards and peripherals.
- The other common electronic circuits.

4. HOW TO ORDER

<u>CA</u>	<u>0612</u>	<u>N</u>	<u>100</u>	<u>J</u>	<u>500</u>	<u>N</u>	I
<u>Series</u>	Size	Dielectric	Capacitance	Tolerance	Rated voltage	<u>Termination</u>	<u>Packaging</u>
CA=Capacitor	0508 =0402*4	N =NP0	Two significant	J =±5%	Two significant digits		T=7" reeled
Array	0612 =0603*4	(C0G) B =X7R	digits followed by no. of zeros. And	K =±10% M =±20%	followed by no. of zeros. And R is in	with 100% Tin	
		Y =Y5V		Z =+80-20%	place of decimal		
			decimal point. eg.:		point.		
			0R5=0.5pF		160=16 VDC		
			1R0=1.0pF 100=10x10 ⁰		250 =25 VDC 500 =50 VDC		
			=10pF				

5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Sy	mbol	S (mm)	BW (mm)	P (mm)
0508	2.00±0.15	1.25±0.15	0.85±0.10	Н	0.20±0.10	0.25±0.10	0.50±0.10
0612	3.20±0.15	1.65±0.15	0.85±0.10	Н	0.30±0.20	0.40±0.15	0.80±0.15



6. GENERAL ELECTRICAL DATA

Dielectric	NPO	X7R	Y5V		
Size	0508, 0612	0612	0612		
Capacitance*	10pF to 470pF	180pF to 100nF	10nF to 100nF		
Capacitance tolerance	J(±5%), K(±10%)	K(±10%), M(±20%)	Z(+80-20%)		
Rated voltage (WVDC)	25, 50V	16V, 25V, 50V	16V, 50V		
Q*/D.F.	Cap<30pF: Q ≥ 400+20C	Ur=50V, ≤ 2.5%	Ur=50V, ≤ 5%		
Q7D.F.	Cap ≥ 30pF: Q	Ur=25V&16V, ≤3.5%	Ur=16V, ≤ 7%		
Insulation resistance at Ur	≥ 10G Ω	≥ 10G Ω or RxC ≥ 500 Ω xF	whichever is less		
Operating temperature	-55 to +125°C		-25 to +85°C		
Capacitance change	±30ppm	30ppm ±15%			
Termination	Ni/Sn (lead free termination)				

^{*} Measured at the conditions of 30~70% related humidity.

NP0: Apply 1.0 \pm 0.2Vrms, 1.0MHz \pm 10% at the condition of 25°C ambient temperature

X7R: Apply 1.0 \pm 0.2Vrms, 1.0kHz \pm 10% at the condition of 25°C ambient temperature

Y5V: Apply 1.0 \pm 0.2Vrms, 1.0kHz \pm 10% at the condition of 20°C ambient temperature

Preconditioning for Class II MLCC: Perform a heat treatment at 150 \pm 10 $^{\circ}$ C for 1 hour, then leave in ambient condition for 24 \pm 2 hours before measurement.

7. CAPACITANCE RANGE

	SIZE		0508(0	402*4)					0612(0603	3*4)		
	DIELECTRIC	NPO		X7R		NF	20		X7R		Y	5V
	RATED VOLTAGE	50V	10V	16V	25V	25V	50V	16V	25V	50V	16V	50V
	10pF (100)	Н				Н	Н					
	15pF (150)	Н				Н	Н					
	22pF (220)	Н				Н	Н					
	33pF (330)	Н				Н	Н					
	47pF (470)	Н				Н	Н					
	68pF (680)	Н				Н	Н					
	100pF (101)	Н				Н	Н					
	150pF (151)	Н				Н	Н					
	180pF (181)	Н				Н	Н		Н	Н		
	220pF (221)	Н				Н	Н		Н	Н		
	330pF (331)		Н	Н	Н	Н	Н		Н	Н		
Cap	470pF (471)		Н	Н	Н	Н	Н		Н	Н		
Capacitance	680pF (681)		Н	Н	Н				Н	Н		
tan	1000pF (102)		Н	Н	Н				Н	Н		
се	1500pF (152)		Н	Н	Н				Н	Н		
	2200pF (222)		Н	Н	Н				Н	Н		
	3300pF (332)		Н	Н	Н				Н	Н		
	4700pF (472)		Н	Н	Н				Н	Н		
	6800pF (682)		Н	Н	Н				Н	Н		
	10nF (103)		Н	Н	Н				Н	Н		Н
	15nF (153)		Н	Н	Н			Н	Н	Н		Н
	22nF (223)		Н	Н	Н			Н	Н	Н		Н
	33nF (333)		Н	Н	Н			Н				Н
	47nF (473)		Н	Н	Н			Н				Н
	68nF (683)		Н	Н	Н			Н				
	100nF (104)		Н	Н	Н			Н			Н	Н

8. PACKAGING DIMENSION AND QUANTITY

Size	Thickness (mm)/Symb	ol.	Paper tape
Size	Thickness (mm)/Symbol		7" reel
0508 (0402X4)	0.85±0.10	Н	4Kpcs
0612 (0603X4)	0.85±0.10	Н	4kpcs

10. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

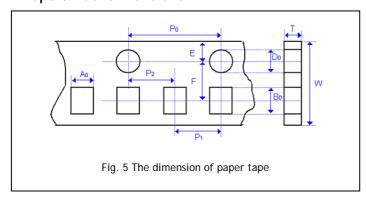
No.	Item	Test Conditions	Requirements
1.	Visual and		* No remarkable defect.
	Mechanical		* Dimensions to conform to individual specification sheet.
2.	Capacitance	1.0±0.2Vrms, 1MHz±10%	* Shall not exceed the limits given in the detailed spec.
3.	Q/ D.F.	At 25°C ambient temperature.	* Cap≥30pF, Q≥1000; Cap<30pF,Q≥400+20C
	(Dissipation		
	Factor)		
4.	Dielectric	* To apply voltage: ≤50V, 250% of rated voltage.	* No evidence of damage or flash over during test.
	Strength	* Duration: 1 to 5 sec.	
		* Charge and discharge current less than 50mA.	
5.	Insulation	To apply rated voltage for max. 120 sec.	≥10GΩ or RxC≥500Ω-F whichever is smaller
	Resistance		
6.	Temperature	With no electrical load.	* Capacitance change: within ±30ppm/°C
	Coefficient	Operating temperature: -55~125°C at 25°C	
7.	Adhesive	* Pressurizing force :	* No remarkable damage or removal of the terminations.
	Strength of	5N≤0603: 10N > 0603	
	Termination	* Test time: 10±1 sec.	
8.	Vibration	* Vibration frequency: 10~55 Hz/min.	* No remarkable damage.
	Resistance	* Total amplitude: 1.5mm	* Cap change and Q/D.F.: To meet initial spec.
		* Test time: 6 hrs. (Two hrs each in three mutually	
		perpendicular directions.)	
9.	Solderability	* Solder temperature: 235±5°C	95% min. coverage of all metalized area.
4.0		* Dipping time: 2±0.5 sec.	
10.	Bending Test	* The middle part of substrate shall be pressurized by means	* No remarkable damage.
		of the pressurizing rod at a rate of about 1 mm per second until	·
		the deflection becomes 1 mm and then the pressure shall be maintained for 5±1 sec.	NPO: within ±5.0% or ±0.5pF whichever is larger. X7R: within ±12.5%
		* Measurement to be made after keeping at room temp. for	Y5V: within ±30%
		24±2 hrs.	This capacitance change means the change of capacitance under
		112 1110.	specified flexure of substrate from the capacitance measured before
			test.)
11.	Resistance to	* Solder temperature: 270±5°C	* No remarkable damage.
	Soldering Heat	* Dipping time: 10±1 sec	* Cap change:
		* Preheating: 120 to 150°C for 1 minute before immerse the	NPO: within ±2.5% or ±0.25pF whichever is larger.
		capacitor in a eutectic solder.	X7R: within ±7.5%
		*Before initial measurement (Class II) only): Perform 150	Y5V: within ±20%
		+0/-10°C for 1hr and then set for 48±4hrs at room temp.	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.
		* Measurement to be made after keeping at room temp. for	* 25% max. leaching on each edge.
40	_	24±2 hrs.(Class I) or 48±4hrs.(Class II)	
12.		* Conduct the five cycles according to the temperatures and	No remarkable damage.
	Cycle	time.	* Cap change :
		*Before initial measurement (Class II) only): Perform 150	NPO: within ±2.5% or ±0.25pF whichever is larger.
		+0/-10°C for 1hr and then set for 48±4hrs at room temp.	X7R: within ±7.5% Y5V: within ±20%
		* Measurement to be made after keeping at room temp. for 24±2 hrs.(Class I) or 48±4hrs.(Class II)	
	i	2712 1113.(Class I) UI 40141113.(Class II)	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.

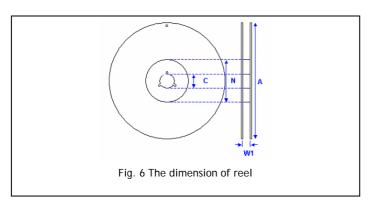
10. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	Item	Test Condition	Requirements
13.	Humidity	* Test temp.: 40±2°C	* No remarkable damage.
	(Damp Heat)	* Humidity: 90~95% RH	* Cap change:
	Steady State	* Test time: 500+24/-0hrs.	NPO: within ±5.0% or ±0.5pF whichever is larger.
	* Measurement to be made after keeping at room temp. for X7		X7R: within ±12.5%
		24±2 hrs.(Class I) or 48±4hrs.(Class II)	Y5V: within ±30%
			* Q/D.F. value:
			NPO: Cap≥30pF, Q≥350; 10pF≤Cap<30pF, Q≥275+2.5C
			Cap<10pF; Q≥200+10C
			X7R: Ur=50V, ≦ 3.0% Ur=16V, ≦ 5.0%
			Y5V: ≦ 7.5%
			* I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller
14.	Humidity	* Test temp.: 40±2°C	* No remarkable damage.
	(Damp Heat)	* Humidity: 90~95%RH	* Cap change:
	Load	* Test time: 500+24/-0 hrs.	NPO: within ±7.5% or ±0.75pF whichever is larger.
		* To apply voltage: rated voltage	X7R: within ±12.5%
		* Measurement to be made after keeping at room temp. for	Y5V: within ±30%
		24±2 hrs.(Class I) or 48±4hrs.(Class II)	* Q/D.F. value:
			NPO: Cap≥30pF, Q≥350; 10pF≤Cap<30pF, Q≥275+2.5C
			Cap<10pF; Q≥200+10C
			X7R: Ur=50V, ≦ 3.0% Ur=16V, ≦ 5.0%
			Y5V: ≦ 7.5%
			* I.R.: ≥ 500MΩ or RxC≥25Ω-F whichever is smaller
15.	High	* Test temp.: NPO, X7R : 125±3°C, Y5V: 85±3°C	* No remarkable damage.
	Temperature	* To apply voltage: 200% of rated voltage.	* Cap change:
	Load	* Test time: 1000+24/-0 hrs.	NPO: within ±3.0% or ±0.3pF whichever is larger.
	(Endurance)	* Measurement to be made after keeping at room temp. for	X7R: within ±12.5%
		24±2 hrs.(Class I) or 48±4hrs.(Class II)	Y5V: within ±30%
			* Q/D.F. value:
			NPO: Cap≥30pF, Q≥350, 10pF≤Cap<30pF, Q≥275+2.5C
			Cap<10pF, Q≥200+10C.
			X7R: Ur=50V, ≦ 3.0% Ur=16V, ≦ 5.0%
			Y5V: ≦ 7.5%
			* I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller

11. APPENDIXES

■ Tape & reel dimensions





Size	0508	0612
Thickness	Т	Т
A_0	1.50±0.10	2.00±0.10
B ₀	2.30±0.10	3.50±0.10
Т	0.95±0.05	0.95±0.05
K ₀	-	-
W	8.00±0.10	8.00±0.10
P ₀	4.00±0.10	4.00±0.10
10xP₀	40.0±0.20	40.0±0.20
P ₁	4.00±0.10	4.00±0.10
P ₂	2.00±0.05	2.00±0.05
D_0	1.55±0.05	1.55±0.05
D_1	-	-
E	1.75±0.05	1.75±0.05
F	3.50±0.05	3.50±0.05

Size	0508,	0612
Reel size	7"	13"
С	13.0+0.5/-0.2	13.0+0.5/-0.2
W ₁	8.4+1.5/-0	8.4+1.5/-0
Α	178.0±1.0	330.0±1.0
N	60.0+1.0/-0	100±1.0

Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. Don't store products in a corrosive environment such as sulfide, chloride gas, or acid. It may cause oxidization of electrode, which easily be resulted in poor soldering.
- b. To store products on the shelf and avoid exposure to moisture.
- c. Don't expose products to excessive shock, vibration, direct sunlight and so on.

Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N_2 within oven are recommended.

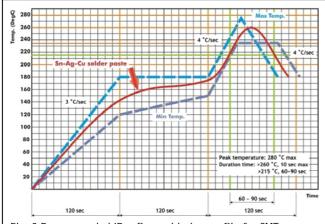


Fig. 8 Recommended IR reflow soldering profile for SMT process with SnAgCu series solder paste.

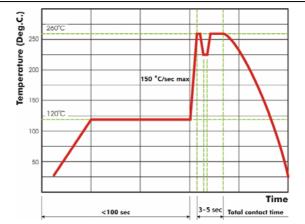


Fig. 9 Recommended wave soldering profile for SMT process with SnAgCu series solder.